

WHAT IS CLAIMED IS:

- Sub B1* →
1. A polyamide resin composition comprising:  
100 parts by weight of a polyamide resin mixture comprising  
(A) 20 to 90% by weight of a polyamide 6 resin, a  
polyamide 66 resin or mixture thereof and  
(B) 10 to 80% by weight of an aromatic polyamide resin;  
and  
(C) 0 to 300 parts by weight of an inorganic filler,  
said aromatic polyamide resin having diamine units  
comprising 10 to 50 mol% of paraxylylenediamine units and 50  
to 90 mol% of methaxylylenediamine units, and aliphatic  
dicarboxylic acid units.
  2. The polyamide resin composition according to claim 1,  
wherein the amount of the inorganic filler (C) blended is 45  
to 150 parts by weight based on 100 parts by weight of the  
polyamide resins (A) and (B).
  3. The polyamide resin composition according to claim 1,  
wherein the amount of the inorganic filler (C) blended is less  
than 45 parts by weight based on 100 parts by weight of the  
polyamide resins (A) and (B).
  - fig* 4. The polyamide resin composition according to claim 1  
further comprising (D) 0.05 to 5 parts by weight of a light  
stabilizer based on 100 parts by weight of the polyamide  
resins (A) and (B).

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5. The polyamide resin composition according to claim 1 further comprising (E) 0.05 to 5 parts by weight of a phenolic antioxidant based on 100 parts by weight of the polyamide resins (A) and (B).

6. The polyamide resin composition according to claim 1 further comprising (F) 0.01 to 5 parts by weight of a copper compound, a halide or mixture thereof based on 100 parts by weight of the polyamide resins (A) and (B).

7. The polyamide resin composition according to claim 1, wherein relative viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is 1.8 to 3.5.

8. The polyamide resin composition according to claim 1, wherein the diamine units comprises 20 to 45 mol% of paraxylylenediamine units and 55 to 80 mol% of methaxylylenediamine units.

9. The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an  $\alpha,\omega$ -straight-chain aliphatic dicarboxylic acid.

10. The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an aliphatic dicarboxylic acid having 6 to 12 carbon atoms.

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11. The polyamide resin composition according to claim 1, wherein relative viscosity of the aromatic polyamide resin is 1.6 to 3.0.

12. The polyamide resin composition according to claim 1, wherein the inorganic filler is a fibrous filler having an average fiber diameter of not more than 14  $\mu\text{m}$  or a powdery, granular or flaky filler having an average particle diameter of not more than 50  $\mu\text{m}$ .

13. The polyamide resin composition according to claim 1, wherein the inorganic filler (C) is selected from the group consisting of glass fiber, talc and mica.

14. The polyamide resin composition according to claim 4, wherein the light stabilizer (D) is selected from the group consisting of hindered amines and benzotriazoles.

15. The polyamide resin composition according to claim 6, wherein the mixture of 0.01 to 2 parts by weight of a copper compound (F') and 0.05 to 3 parts by weight of an alkali metal halide (F'') based on 100 parts by weight of the polyamide resins (A) and (B) is used.

16. The polyamide resin composition according to claim 1, wherein the whole of the component (A) is a polyamide 6 resin.

17. A polyamide resin composition comprising:

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100 parts by weight of a polyamide resin mixture comprising

(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and

(B) 10 to 80% by weight of an aromatic polyamide resin; and

(C) 0 to 300 parts by weight of an inorganic filler,

said aromatic polyamide resin mainly comprising a polyamide obtained from polycondensation reaction of a diamine mixture comprising 10 to 50 mol% of paraxylylenediamine and 50 to 90 mol% of methaxylylenediamine, and an aliphatic dicarboxylic acid.

18. A molded article for outdoor use, obtained by molding a polyamide resin composition as defined in claim 1.

19. The molded article according to claim 18, obtained by a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is lower than that of the aromatic polyamide resin (B).

20. The molded article according to claim 18, obtained by molding a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is higher than that of the aromatic polyamide resin (B).

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A1

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